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Patent

Docket No.: 53434USA8C.009

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Peter B. Hogerton, Kevin Yu Chen, Joel A. Gerber  
and Robert L.D. Zenner

Serial No.: 09/690,600

Filed: October 17, 2000

For: SOLVENT ASSISTED BURNISHING OF  
PRE-UNDERFILLED SOLDER-  
BUMPED WAFERS FOR FLIPCHIP  
BONDING

Group Art Unit:

Examiner:

TECHNOLOGY CENTER 3700  
SEP -6 2001  
329

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**REQUEST FOR CORRECTION OF FILING RECEIPT**

Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

Please issue a corrected filing receipt for the above application showing that inventor Joel A. Gerber resides in the state of Minnesota, not Georgia as evidenced by the Declaration mailed on February 6, 2001.

Respectfully submitted,

Matthew B. McNutt  
Registration No. 38,454

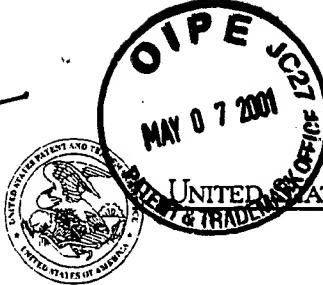
Date: 4/30/2001  
Office of Intellectual Property Counsel  
3M Innovative Properties Company  
P.O. Box 33427  
St. Paul, Minnesota 55133-3427  
Telephone: (512) 984-3958

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231 on:

5-1-01

Signed:

Tom Sanders



## UNITED STATES PATENT AND TRADEMARK OFFICE

COMMISSIONER FOR PATENTS  
 UNITED STATES PATENT AND TRADEMARK OFFICE  
 WASHINGTON, D.C. 20591-3192  
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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	PTO FEE RECD	ATTY DOCKET NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/690,600	10/17/2000	3729	974	53434-USA8C.009	17	23	9 4 ✓

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 APR 27 2001

M.B. McNUTT

Attention: Matthew B. McNutt  
 Office of Intellectual Property Counsel  
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APR 23 2001

REFERRED TO

CONFIRMATION NO. 2588

UPDATED FILING RECEIPT



OC000000005973204

Date Mailed: 04/17/2001

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the PTO processes the reply to the Notice, the PTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

**Applicant(s)**

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 Kevin Yu Chen, San Diego, CA;  
 Joel A. Gerber, Orono, ~~GA~~, MN  
 Robert L. D. Zenner, Minneapolis, MN;

**Domestic Priority data as claimed by applicant**

THIS APPLICATION IS A CIP OF 08/986,661 12/08/1997

**Foreign Applications**

If Required, Foreign Filing License Granted 11/24/2000

Projected Publication Date: N/A

Non-Publication Request: No

Early Publication Request: No

**Title**

Solvent assisted burnishing of pre-underfilled solder bumped wafers for flipchip bonding